ON Semiconductor

10/15/2019

Base Part		**HF**	
Orderable Part	**FCPF380N60-F152**	**Total weight (mg)**	**1604.75**

Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	13.5	Silicon (Si)	7440-21-3	100
Die Attach Solder	12	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	519.74	Nickel (Ni)	7440-02-0	0.010005
		Iron (Fe)	7439-89-6	0.10005003
		Copper (Cu)	7440-50-8	99.85742871
		Phosphorus (P)	7723-14-0	0.03251626
Mold Compound-Black	1049.51	Ortho Cresol Novolac Resin	29690-82-2	10.62876962
		Carbon Black (C)	1333-86-4	0.27727225
		Silica (SiO2)	14464-46-1	81.23791103
		Phenolic Resin (Novolac)	9003-35-4	7.85604711
Plating	5	Tin (Sn)	7440-31-5	100
Wire Bond - Al	5	Nickel (Ni)	7440-02-0	0.00500638
		Aluminum (Al)	7429-90-5	99.99499362

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF